



LAYER-STACK
 01-16
 01-20

Sym	Nº	Mils	MM	Qty	Plated
+	1	24	0.60	83	YES
x	2	32	0.81	8	YES
□	3	40	1.02	142	YES
◇	4	51	1.30	4	YES
⊗	5	67	1.70	2	YES
⊗	6	125	3.18	2	NOT

1. Material
 - 1.1. All material to be RoHS compliant.
 - 1.2. All material to be tolerant of Pb-free solder process temperatures.
 - 1.3. All material, including solder mask and legends, shall have a UL flammability rating of 94V-0.
Date code and manufacturers UL symbol/type shall be permanently marked or etched on the board.
 - 1.4. 2 oz finished copper weight, nominal (1oz plating over 1oz).
 - 1.5. Finish: ENIG.
2. Solder Mask
 - 2.1. Solder mask both sides, with blue color.
 - 2.2. Encroach primary side via pads but prevent solder mask in via holes.
 - 2.3. No solder mask on secondary side via pads.
 - 2.4. No solder mask on component pads
 - 2.5. Solder mask must be present between adjacent SMT pads.
3. Silkscreen
 - 3.1. No silkscreen allowed on exposed lands or in holes.
4. Dimensions
 - 4.1. Overall Thickness: .062" +/- 10%
 - 4.2. Hole tolerance +/- .005"